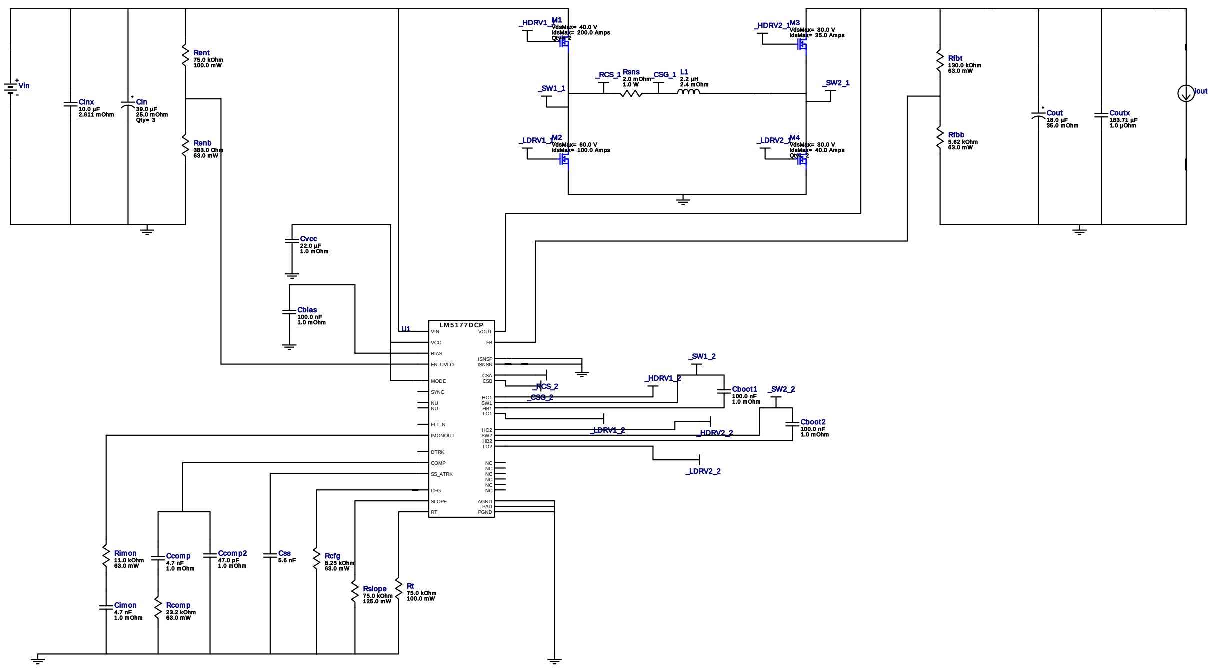
VinMin = 20.0V
VinMax = 36.0V
Vout = 24.0V
Iout = 15.0A

Device = LM5177DCPR
Topology = Buck_Boost
Created = 2024-02-01 18:43:09.688
BOM Cost = NA
BOM Count = 32
Total Pd = 5.66W

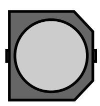
WEBENCH ® Design Report

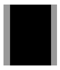
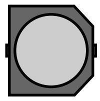
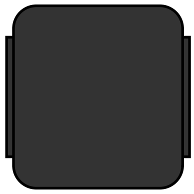
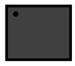
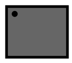
Design : 61 LM5177DCPR
LM5177DCPR 20V-36V to 24.00V @ 15A



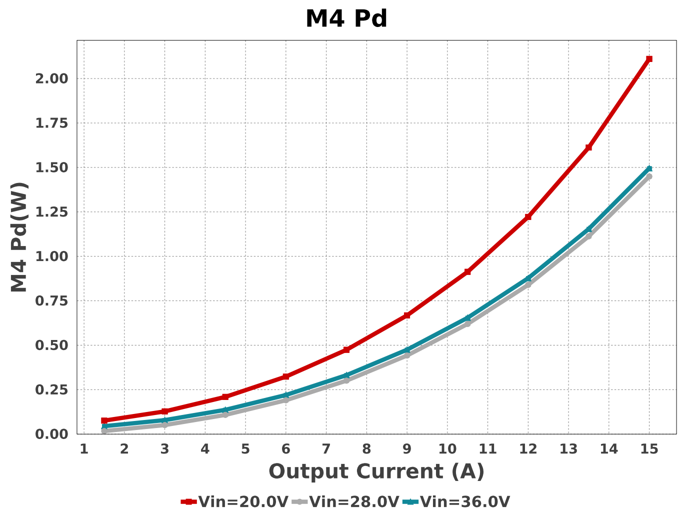
Electrical BOM

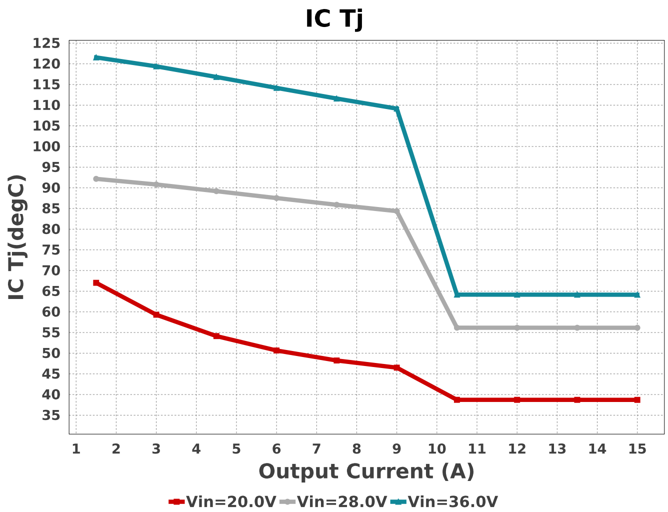
Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Cbias	Yageo	CC0805KRX7R7BB104 Series= X7R	Cap= 100.0 nF ESR= 1.0 mOhm VDC= 16.0 V IRMS= 0.0 A	1	$0.02	0805 7 mm^2
Cboot1	Yageo	CC0805KRX7R8BB104 Series= X7R	Cap= 100.0 nF ESR= 1.0 mOhm VDC= 25.0 V IRMS= 0.0 A	1	$0.02	0805 7 mm^2
Cboot2	Yageo	CC0805KRX7R8BB104 Series= X7R	Cap= 100.0 nF ESR= 1.0 mOhm VDC= 25.0 V IRMS= 0.0 A	1	$0.02	0805 7 mm^2
Ccomp	MuRata	GRM2165C1H472JA01D Series= C0G/NP0	Cap= 4.7 nF ESR= 1.0 mOhm VDC= 50.0 V IRMS= 0.0 A	1	$0.04	0805 7 mm^2
Ccomp2	MuRata	GRM1555C1E470JA01D Series= C0G/NP0	Cap= 47.0 pF ESR= 1.0 mOhm VDC= 25.0 V IRMS= 0.0 A	1	$0.01	0402 3 mm^2
Cimon	MuRata	GRM2165C1H472JA01D Series= C0G/NP0	Cap= 4.7 nF ESR= 1.0 mOhm VDC= 50.0 V IRMS= 0.0 A	1	$0.04	0805 7 mm^2
Cin	Panasonic	50SVPF39M Series= SVPF	Cap= 39.0 uF ESR= 25.0 mOhm VDC= 50.0 V IRMS= 3.8 A	3	$1.15	CAPSMT_62_E12 106 mm^2

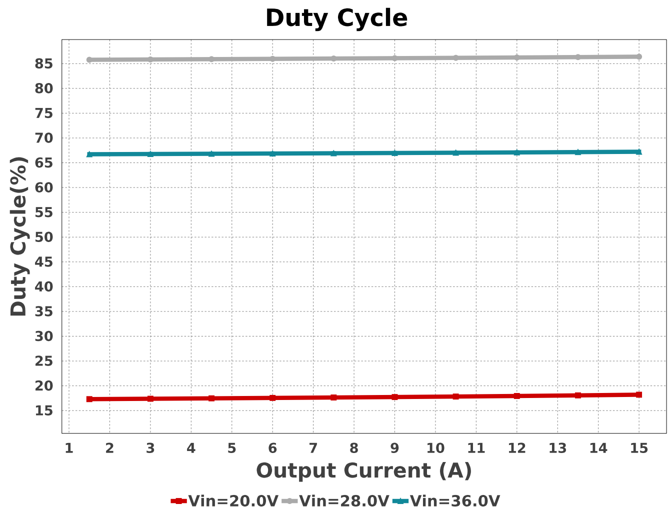


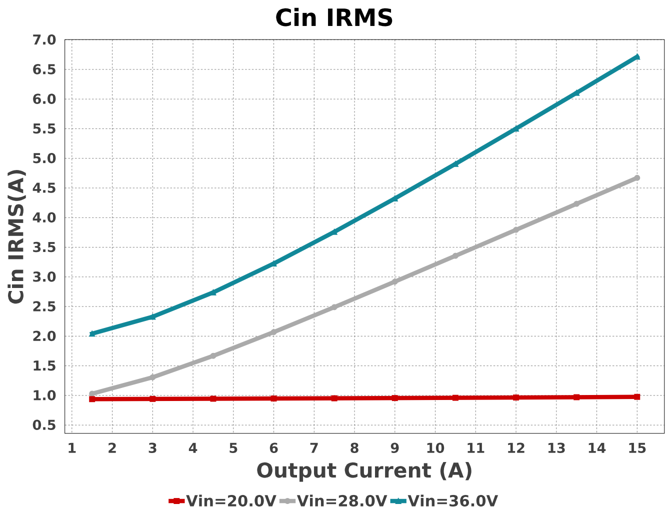
Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Cinx	TDK	C5750X5R1H106K230KA Series= X5R	Cap= 10.0 uF ESR= 2.611 mOhm VDC= 50.0 V IRMS= 5.6501 A	1	\$0.69	 2220_250 54 mm^2
Cout	Panasonic	50SVPF18M Series= SVPF	Cap= 18.0 uF ESR= 35.0 mOhm VDC= 50.0 V IRMS= 2.7 A	1	\$0.70	 CAPSMT_62_E7 106 mm^2
Coutx	CUSTOM	CUSTOM Series= ?	Cap= 183.71 uF ESR= 1.0 uOhm VDC= 48.0 V IRMS= 410.52 uA	1	NA	CUSTOM 0 mm^2
Css	TDK	CGA4C2C0G1H562J060AA Series= C0G/NP0	Cap= 5.6 nF VDC= 50.0 V IRMS= 0.0 A	1	\$0.05	0805 7 mm^2
Cvcc	MuRata	GRM188R60J226MEA0D Series= X5R	Cap= 22.0 uF ESR= 1.0 mOhm VDC= 6.3 V IRMS= 6.0 A	1	\$0.04	0603 5 mm^2
L1	Vishay-Dale	IHLP6767GZER2R2M01	L= 2.2 µH 2.4 mOhm	1	\$2.32	 IHLP-6767GZ 367 mm^2
M1	Texas Instruments	CSD18513Q5A	VdsMax= 40.0 V IdsMax= 200.0 Amps	2	\$0.26	 TRANS_NexFET_Q5A 55 mm^2
M2	Texas Instruments	CSD18540Q5B	VdsMax= 60.0 V IdsMax= 100.0 Amps	1	\$0.75	 DNK0008A 56 mm^2
M3	Texas Instruments	CSD17577Q3A	VdsMax= 30.0 V IdsMax= 35.0 Amps	1	\$0.15	 DNH0008A 18 mm^2
M4	Texas Instruments	CSD17578Q3A	VdsMax= 30.0 V IdsMax= 40.0 Amps	2	\$0.13	 DNH0008A 18 mm^2
Rcfg	Vishay-Dale	CRCW04028K25FKED Series= CRCW..e3	Res= 8.25 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm^2
Rcomp	Vishay-Dale	CRCW040223K2FKED Series= CRCW..e3	Res= 23.2 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm^2
Renb	Vishay-Dale	CRCW0402383RFKED Series= CRCW..e3	Res= 383.0 Ohm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm^2
Rent	Vishay-Dale	CRCW060375K0FKEA Series= CRCW..e3	Res= 75.0 kOhm Power= 100.0 mW Tolerance= 1.0%	1	\$0.01	0603 5 mm^2
Rfbb	Vishay-Dale	CRCW04025K62FKED Series= CRCW..e3	Res= 5.62 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm^2
Rfbt	Vishay-Dale	CRCW0402130KFKED Series= CRCW..e3	Res= 130.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm^2
Rimon	Vishay-Dale	CRCW040211K0FKED Series= CRCW..e3	Res= 11.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm^2

Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Rslope	Vishay-Dale	CRCW080575K0FKEA Series= CRCW..e3	Res= 75.0 kOhm Power= 125.0 mW Tolerance= 1.0%	1	$0.01	0805 7 mm^2
Rsns	Stackpole Electronics Inc	CSNL1206FT2L00 Series= CSNL	Res= 2.0 mOhm Power= 1.0 W Tolerance= 1.0%	1	$0.19	1206 11 mm^2
Rt	Vishay-Dale	CRCW060375K0FKEA Series= CRCW..e3	Res= 75.0 kOhm Power= 100.0 mW Tolerance= 1.0%	1	$0.01	0603 5 mm^2
U1	Texas Instruments	LM5177DCPR	Switcher	1	$2.80	DCP0038A 98 mm^2

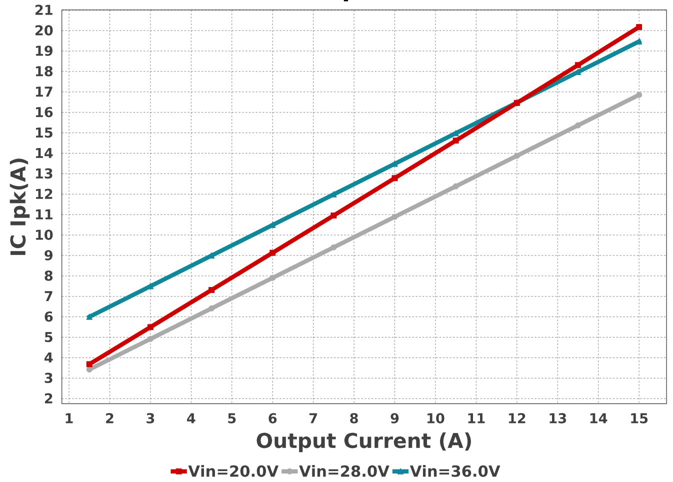




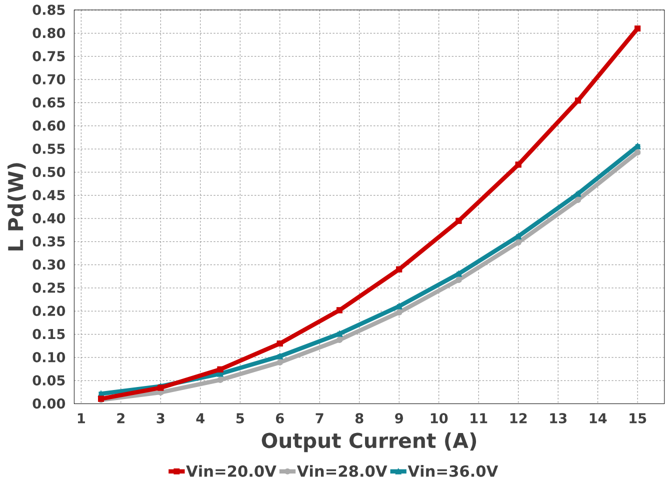




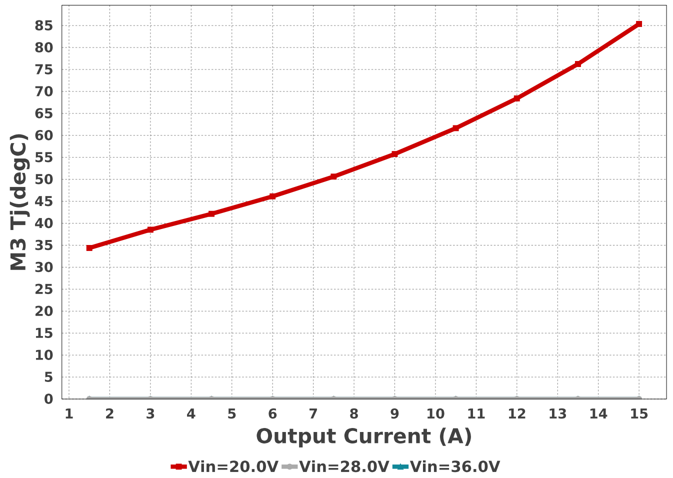
IC Ipk



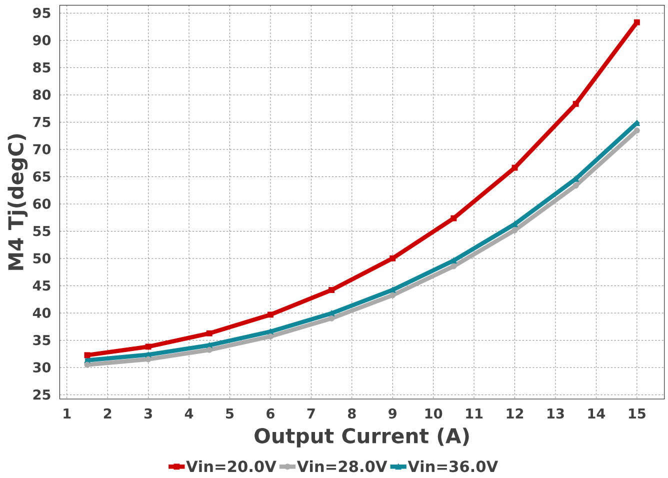
L Pd



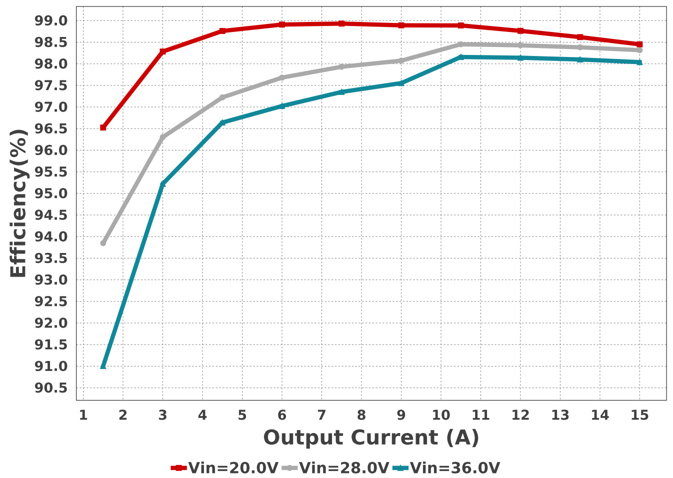
M3 Tj



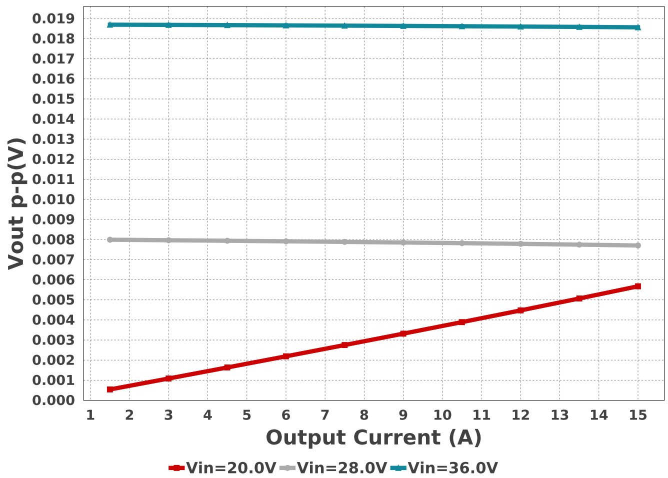
M4 Tj



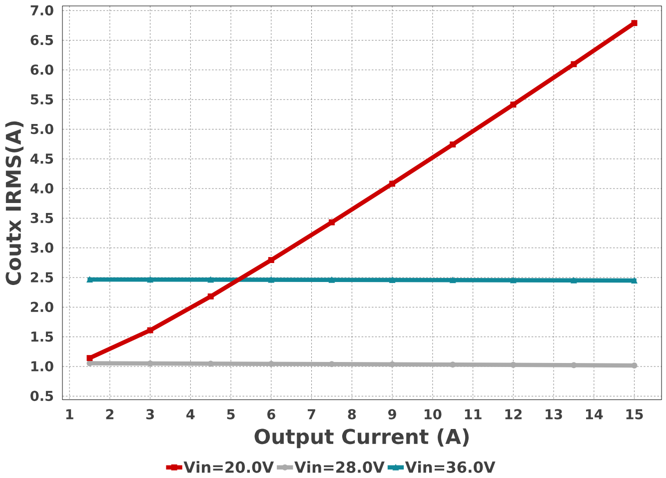
Efficiency



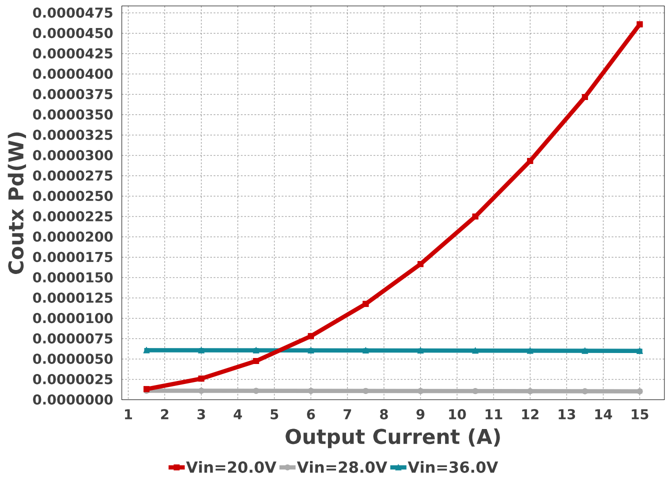
Vout p-p



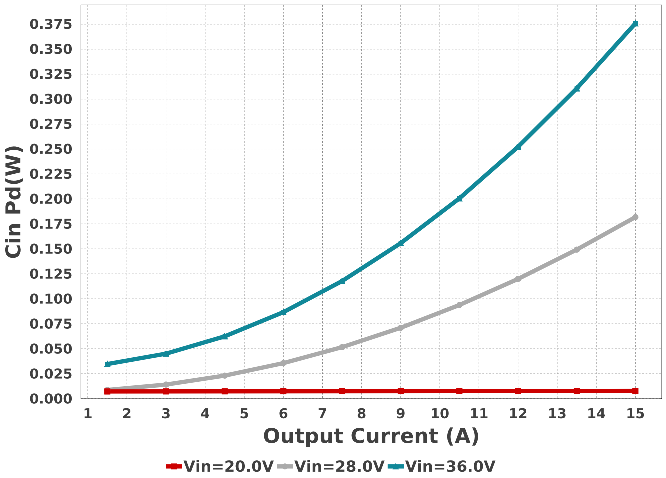
Coutx IRMS



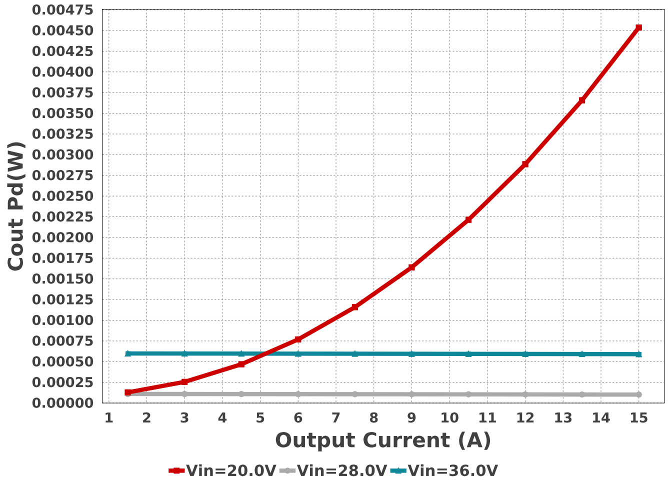
Coutx Pd



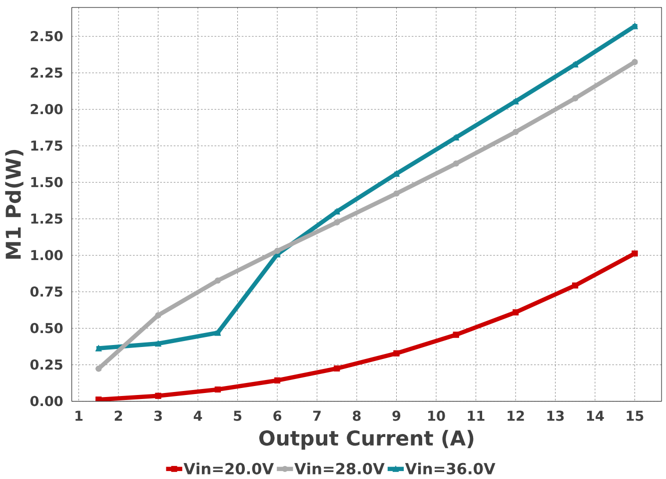
Cin Pd



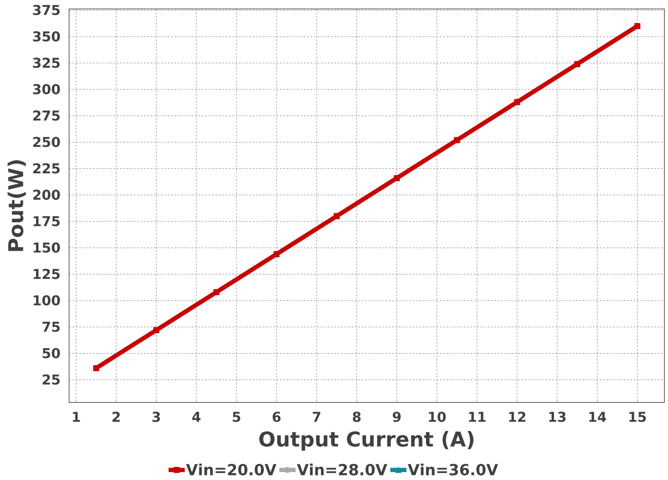
Cout Pd

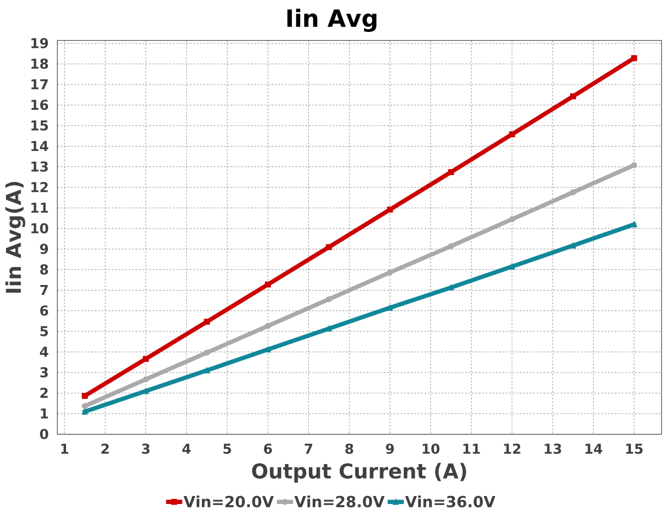


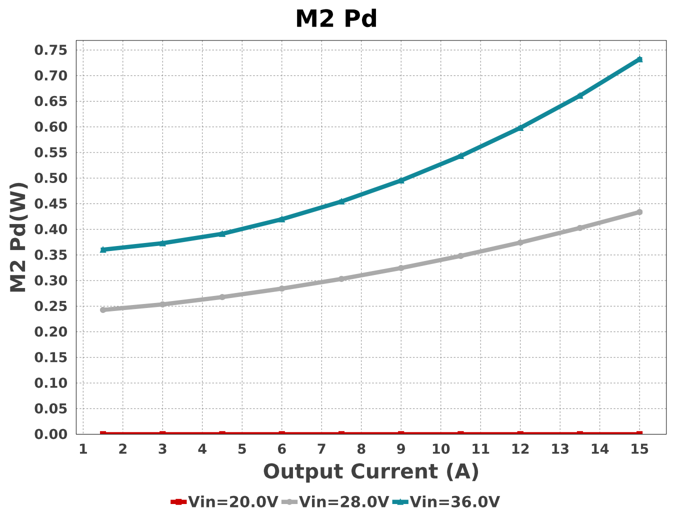
M1 Pd

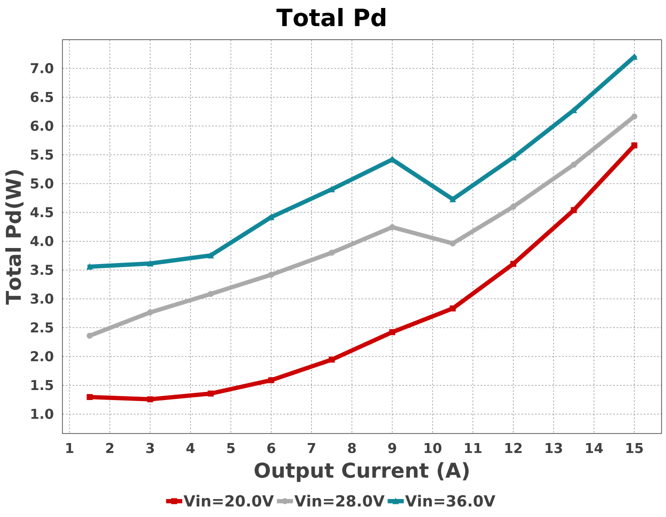


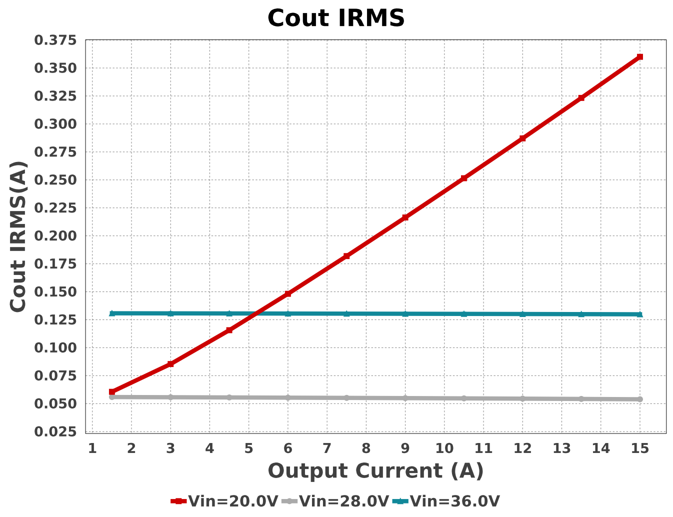
Pout

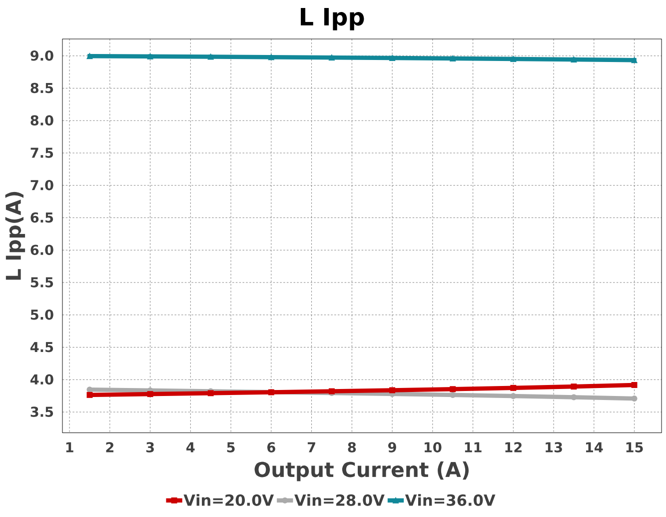


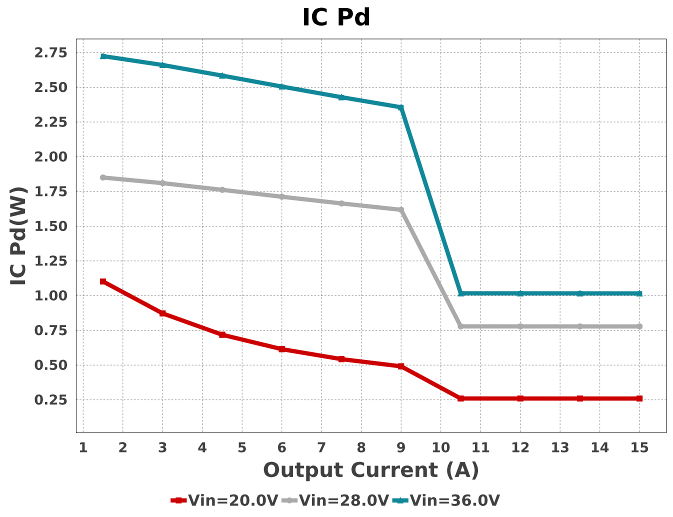

Iin Avg
Iin Avg(A)
Output Current (A)
Vin=20.0V
Vin=28.0V
Vin=36.0V

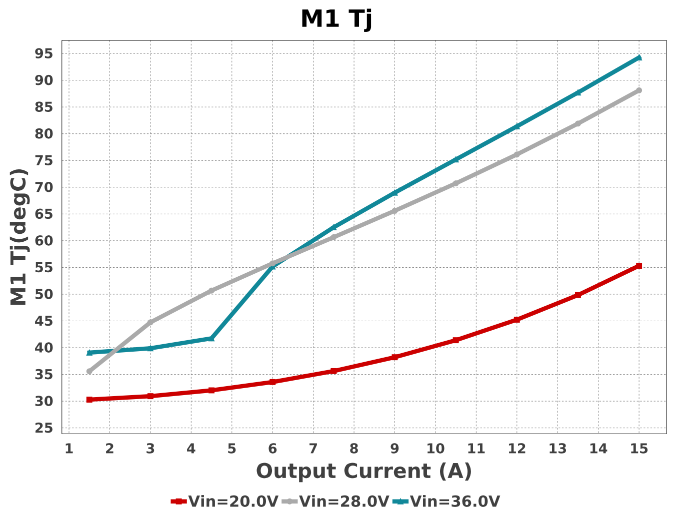

M2 Pd
M2 Pd(W)
Output Current (A)
Vin=20.0V
Vin=28.0V
Vin=36.0V

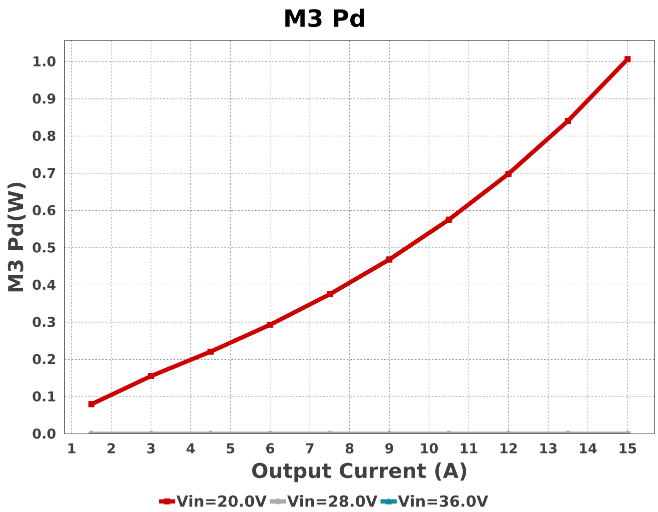

Total Pd
Total Pd(W)
Output Current (A)
Vin=20.0V
Vin=28.0V
Vin=36.0V

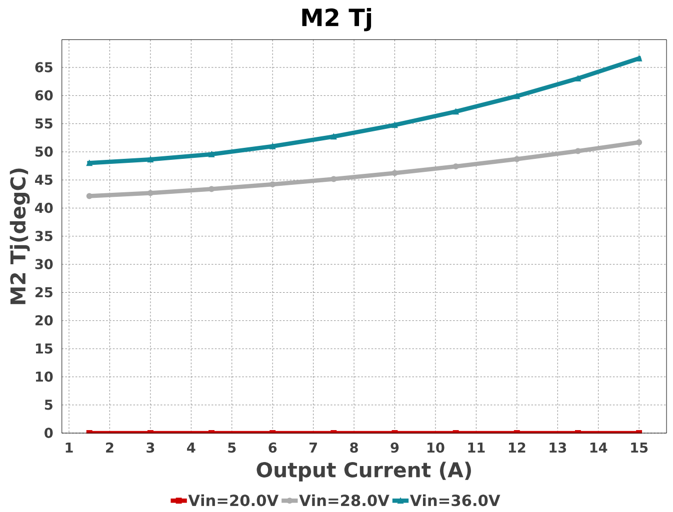

Cout IRMS
Cout IRMS(A)
Output Current (A)
Vin=20.0V
Vin=28.0V
Vin=36.0V

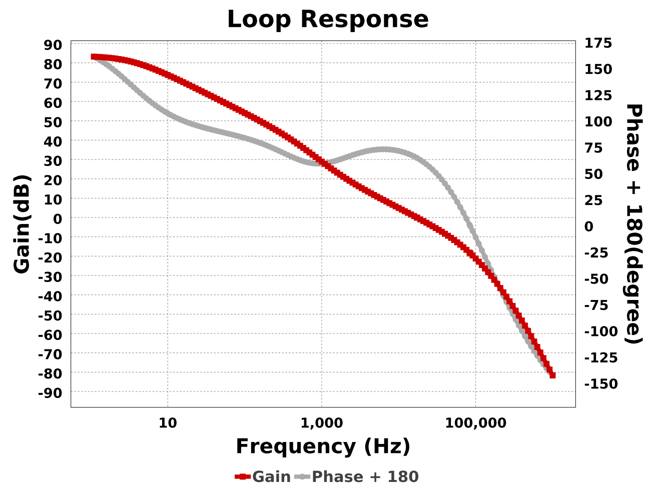

L Ipp
L Ipp(A)
Output Current (A)
Vin=20.0V
Vin=28.0V
Vin=36.0V


IC Pd
IC Pd(W)
Output Current (A)
Vin=20.0V
Vin=28.0V
Vin=36.0V









Operating Values

#	Name	Value	Category	Description
1.	BOM Count	32		Total Design BOM count
2.	Total BOM	NA		Total BOM Cost
3.	Cin IRMS	976.014 mA	Capacitor	Input capacitor RMS ripple current
4.	Cin Pd	7.938 mW	Capacitor	Input capacitor power dissipation
5.	Cout IRMS	359.985 mA	Capacitor	Output capacitor RMS ripple current
6.	Cout Pd	4.536 mW	Capacitor	Output capacitor power dissipation
7.	Coutx IRMS	6.79 A	Capacitor	Output capacitor_x RMS ripple current
8.	Coutx Pd	46.1 µW	Capacitor	Output capacitor_x power loss
9.	IC Ipk	20.171 A	IC	Peak switch current in IC
10.	IC Pd	259.24 mW	IC	IC power dissipation
11.	IC Tj	38.71 degC	IC	IC junction temperature
12.	IC Tolerance	10.0 mV	IC	IC Feedback Tolerance
13.	ICThetaJA	33.6 degC/W	IC	IC junction-to-ambient thermal resistance
14.	Iin Avg	18.283 A	IC	Average input current
15.	L Ipp	3.918 A	Inductor	Peak-to-peak inductor ripple current
16.	L Pd	810.16 mW	Inductor	Inductor power dissipation
17.	M1 Pd	1.013 W	Mosfet	M1 MOSFET total power dissipation
18.	M1 Tj	55.317 degC	Mosfet	M1 MOSFET junction temperature
19.	M2 Pd	0.0 W	Mosfet	M2 MOSFET total power dissipation
20.	M2 Tj	0.0 degC	Mosfet	M2 MOSFET junction temperature
21.	M3 Pd	1.007 W	Mosfet	M1 MOSFET total power dissipation
22.	M3 Tj	85.361 degC	Mosfet	M1 MOSFET junction temperature
23.	M4 Pd	2.11 W	Mosfet	M2 MOSFET total power dissipation
24.	M4 Tj	93.314 degC	Mosfet	M2 MOSFET junction temperature
25.	Cin Pd	7.938 mW	Power	Input capacitor power dissipation
26.	Cout Pd	4.536 mW	Power	Output capacitor power dissipation
27.	Coutx Pd	46.1 µW	Power	Output capacitor_x power loss
28.	IC Pd	259.24 mW	Power	IC power dissipation
29.	L Pd	810.16 mW	Power	Inductor power dissipation
30.	M1 Pd	1.013 W	Power	M1 MOSFET total power dissipation
31.	M2 Pd	0.0 W	Power	M2 MOSFET total power dissipation
32.	M3 Pd	1.007 W	Power	M1 MOSFET total power dissipation

#	Name	Value	Category	Description
33.	M4 Pd	2.11 W	Power	M2 MOSFET total power dissipation
34.	Total Pd	5.664 W	Power	Total Power Dissipation
35.	Cross Freq	24.409 kHz	System Information	Bode plot crossover frequency
36.	Duty Cycle	18.203 %	System Information	Duty cycle
37.	Efficiency	98.451 %	System Information	Steady state efficiency
38.	FootPrint	1.358 k mm^2	System Information	Total Foot Print Area of BOM components
39.	Frequency	403.997 kHz	System Information	Switching frequency
40.	Gain Marg	-6.932 dB	System Information	Bode Plot Gain Margin
41.	Iout	15.0 A	System Information	Iout operating point
42.	Low Freq Gain	79.92 dB	System Information	Gain at 1Hz
43.	Mode	CCM	System Information	Conduction Mode
44.	Phase Marg	46.157 deg	System Information	Bode Plot Phase Margin
45.	Pout	360.0 W	System Information	Total output power
46.	Vin	20.0 V	System Information	Vin operating point
47.	Vout	24.0 V	System Information	Operational Output Voltage
48.	Vout Actual	24.132 V	System Information	Vout Actual calculated based on selected voltage divider resistors
49.	Vout Tolerance	2.956 %	System Information	Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable
50.	Vout p-p	5.674 mV	System Information	Peak-to-peak output ripple voltage

Design Inputs

Name	Value	Description
Iout	15.0	Maximum Output Current
VinMax	36.0	Maximum input voltage
VinMin	20.0	Minimum input voltage
Vout	24.0	Output Voltage
base_pn	LM5177	Base Product Number
source	DC	Input Source Type
Ta	30.0	Ambient temperature

WEBENCH® Assembly

Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of Cin and Cout, and the inductance and DC resistance of L1 before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

Soldering Component to Board

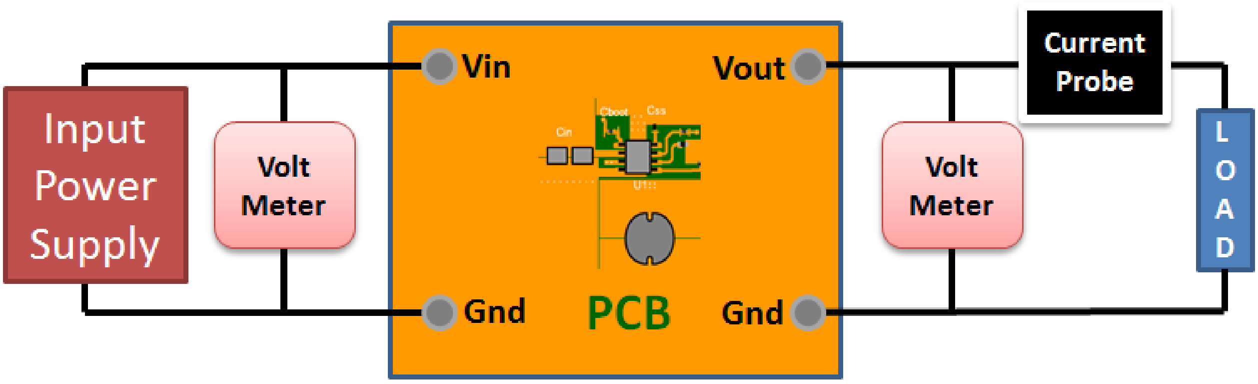
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab town to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 20.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to Vin and GND. Connect a digital volt meter and a load if needed to set the minimum Iout of the design from Vout and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between Vin and GND, a load is connected between Vout and GND and a current meter is connected in series between Vout and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.



Design Assistance

1. Master key : A95EBBFF9A18ACFD34ABF735856AFE62[v1]

2. **LM5177** Product Folder : http://www.ti.com/product/LM5177 : contains the data sheet and other resources.

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